## 503607705 12/11/2015

# **PATENT ASSIGNMENT COVER SHEET**

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3654336

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
ALAN ROTH	12/10/2015
ERIC SOENEN	12/11/2015

### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14956061

#### **CORRESPONDENCE DATA**

**Fax Number:** (703)518-5499

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 7036841111 Email: tsmc@ipfirm.com

**Correspondent Name:** HAUPTMAN HAM, LLP (TSMC)

Address Line 1: 2318 MILL ROAD SUITE 1400

Address Line 4: ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER: T5057-1155U	
NAME OF SUBMITTER: RANDY A. NORANBROCK	
SIGNATURE:	/Randy A. Noranbrock/
DATE SIGNED:	12/11/2015

**Total Attachments: 1** 

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PATENT 503607705 REEL: 037270 FRAME: 0636

## ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

1) Alan ROTH

Name: Eric SOENEN

**RECORDED: 12/11/2015** 

Eric SOENEN

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

<u>CHA</u>	RGE PUMP CIRCUIT		**************************************	
(a)	for which an application for United States Letters Patent was filed of United States Patent Application No. 14/956,061		2015-12-01 and identified	
(b)	for which an application for United States			
au Onn continu Propert	undersigned hereby authorizes and request ed States Letters Patent which may be gran ations-in-part thereof, and the right to all y to the said ASSIGNEE, for its interest as hat the attorneys of record in said applicatio	nted therefore and any and all benefits under the Internation ASSIGNEE, its successors, and shall hereafter act on behalf	l extensions, divisions, in onal Convention for the assigns and legal represe of said ASSIGNEE;	reissues, continuations, or e Protection of Industrial entatives; the undersigned
ASSIGI applicat ASSIGI he inve	AND the undersigned hereby agrees to ion for and obtaining original, divisional, re NEE, its successors, assigns and legal represons for patent based thereon, growing out NEE, its successors, assigns and legal represention hereby transferred.	rissued or extended Letters Pa sentatives, and without furthe it of or related to the said in	tent of the United States r remuneration, in and to execute	s, upon request of the said to any improvements, and the any papers by the said
l)	On the date indicated aside my signature:	Date:	12/10/	•

Date:

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REEL: 037270 FRAME: 0637